

MATERIAL DECLARATION SHEET

BOURNS®

Material Number	CRL1206(0.01~0.091Ω) Series			
Product Line	Thick Film Chip Resistors			
Compliance Date	2018/10/05			
RoHS Compliant	Yes	MSL	1/2/3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Material s Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	CRXXXX	8.16145215	Aluminum oxide	1344-28-1	96%	53.42%	55.65%
				Silicon dioxide	14808-60-7	4%	2.23%	
	Conductor Layer (Bottom)	AZZ.002.XXXX	0.7788177	Silver	7440-22-4	95%	5.04%	5.31%
				Glass	65997-17-3	5%	0.27%	
	Resistive Element	Ni-Cu-Mn	0.33294090	Manganese	7439-96-5	1.5%	0.03%	2.27%
				Copper	7440-50-8	63%	1.43%	
				Nickel	7440-02-0	35.5%	0.81%	
	Over-Coating	AZZ.002.1057A	0.0645348	Epoxy	29690-82-2	100%	0.44%	0.44%
	Marking	ZM-400WF1	0.0044001	Epoxy	25068-38-6	100%	0.03%	0.03%
	End Terminal	AZZ.003.0048	0.0337341	Nickel	7440-02-0	80%	0.18%	0.23%
				Chromium	7440-47-3	20%	0.05%	
	Cu Plating	Cu	3.4496784	Copper	7440-50-8	100%	23.52%	23.52%
	Ni Plating	Ni	0.9203542	Nickel	7440-02-0	100%	6.28%	6.28%
	Sn Plating	Sn	0.9210876	Tin	7440-31-5	100%	6.28%	6.28%
		Total	14.667					

This Document was updated on: 2018/10/05 ← the Date you completed fulfillment.

Important remarks: It is the responsibility of the user to verify they are accessing the latest version.